PATENT COOPERATION TRACTO PCT/PTO 1 1 0CT 2003/00862

From the INTERNATION

BURFALL

NOTIFICATION OF TRANSMITTAL OF COPIES OF TRANSLATION OF THE INTERNATIONAL PRELIMINARY EXAMINATION REPORT

(PCT Rule 72.2)

To

NAKANO, Minoru c/o Sumitomo Electric Industries, Ltd. 1-3, Shimaya 1-chome, Konohana-ku Osaka-shi, Osaka 554-0024 IAPON



Date of mailing (day/month/year) 27 January 2005 (27.01.2005)

Applicant's or agent's file reference 103166-WO-00

International application No. PCT/JP2003/008624 IMPORTANT NOTIFICATION

International filing date (day/month/year) 07 July 2003 (07.07 2003)

Applicant

SUMITOMO ELECTRIC INDUSTRIES, LTD, et al.

1. Transmittal of the translation to the applicant.

The International Bureau transmits herewith a copy of the English translation made by the International Bureau of the international preliminary examination report established by the International Preliminary Examining Authority.

2. Transmittal of the copy of the translation to the elected Offices.

The International Bureau notifies the applicant that copies of that translation have been transmitted to the following elected Offices requiring such translation:

AZ, CA, CH, CN, CO, EP, GH, KG, KP, KR, MK, MZ, RO, RU, TM

The following elected Offices, having waived the requirement for such a transmittal at this time, will receive copies of that translation from the International Bureau only upon their request:

AE, AG, AL, AM, AP, AT, AU, BA, BB, BG, BR, BY, BZ, CR, CU, CZ, DE, DK, DM, DZ, EA, EC, EE, ES, FI, GB, GD, GE, GM, HR, HU, ID, IL, IN, IS, KE, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MN, MW, MX, NI, NO, NZ, OA, OM, PG, PH, PL, PT, SC, SD, SE, SG, SK, SL, SY, TJ, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW

Reminder regarding translation into (one of) the official language(s) of the elected Office(s).

The applicant is reminded that, where a translation of the international application must be furnished to an elected Office, that translation must contain a translation of any annexes to the international preliminary examination report.

It is the applicant's responsibility to prepare and furnish such translation directly to each elected Office concerned (Rule 74.1). See Volume II of the PCT Applicant's Guide for further details.

Best Available Copy

The International Bureau of WIPO 34, chemin des Colombettes 1211 Geneva 20, Switzerland

Authorized officer

Yoshiko Kuwahara

Facsimile No.+41 22 740 14 35

Facsimile No.+41 22 338 90 90

Translation

PERATION TREATY Rec'd PCT/PTO 1

INTERNATIONAL PRELIMINARY EXAMINATION REPORT

(PCT Article 36 and Rule 70)

Applicant's or agent's file reference 103166-WO-00	FOR FURTHER ACT	TION See Notific	ation of Transmittal of International Examination Report (Form PCT/IPEA/416)
International application No.	International filing date	(day/month/year)	Priority date (day/month/year)
PCT/JP2003/008624	07 July 2003 (0	07.07.2003)	17 July 2002 (17.07.2002)
International Patent Classification (IPC) or n H01L 23/36, 23/373	ational classification and	IPC	
Applicant SUM	IITOMO ELECTRIC	: INDUSTRIES,	LTD.
and is transmitted to the applicant a	ccording to Article 36.		national Preliminary Examining Authority
This REPORT consists of a total of	5 sheets, i	ncluding this cover s	ineet.
amended and are the basis for 70.16 and Section 607 of the	or this report and/or sheets Administrative Instruction	ons under the PCT).	on, claims and/or drawings which have been ttions made before this Authority (see Rule
These annexes consist of a to	otal ofsl	heets.	
 This report contains indications related 	ating to the following item	ns:	
I Basis of the report			
II Priority			
III Non-establishment	of opinion with regard to	novelty, inventive s	tep and industrial applicability
IV Lack of unity of in			
V Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement			
VI Certain documents cited			
VII Certain defects in	the international applicati	on	
VIII Certain observatio	ns on the international ap	plication	
Date of submission of the demand		Date of completion	of this report
04 December 2003 (04.12.2003)		2	6 May 2004 (26.05.2004)
Name and mailing address of the IPEA/JP		Authorized officer	
Facsimile No.		Telephone No.	

Form PCT/IPEA/409 (cover sheet) (July 1998)

VINTERNATIONAL PRELIMINARY EXAMINATION REPORT

Internation Polication No	э.
---------------------------	----

PCT/JP2003/008624

	or the rep	
. With		the elements of the international application:*
\boxtimes	the inten	national application as originally filed
n	the desci	ription:
	pages	, as originally filed
	pages	, filed with the demand
	pages	, filed with the letter of
	_	i
	the clain	, as originally filed
	pages	, as amended (together with any statement under Article 19
	pages	, filed with the demand
	pages	, filed with the letter of
	pages	, , , , , , , , , , , , , , , , , , , ,
	the drav	vings: , as originally filed
	pages	, as originally filed
	pages	
	pages	, filed with the letter of
П	the seque	nce listing part of the description:
لــا	pages	as originally filed
	pages	, filed with the demand
	pages	, filed with the letter of
		o the language, all the elements marked above were available or furnished to this Authority in the language in which
The	ese elemen	its were available or furnished to this Authority in the following language
· [.	the lan	guage of a translation furnished for the purposes of international search (under Rule 23.1(b)).
	7	revises of publication of the international application (under Rule 48.3(b)).
	the lar	nguage of the translation furnished for the purposes of international preliminary examination (under Rule 55.2 and/
3. W	ith regard	to any nucleotide and/or amino acid sequence disclosed in the international application, the international examination was carried out on the basis of the sequence listing:
lੌ		ned in the international application in written form.
l ⊨		ogether with the international application in computer readable form.
l F		hed subsequently to this Authority in written form.
l ⊨		hed subsequently to this Authority in computer readable form.
[The s	statement that the subsequently furnished written sequence listing does not go beyond the disclosure in the
	The s	automated that the information recorded in computer readable form is identical to the written sequence listing has furnished.
l _		
4.	The a	mendments have resulted in the cancellation of:
		the description, pages
1		the claims, Nos.
1	П	the drawings, sheets/fig
5.	This r	eport has been established as if (some of) the amendments had not been made, since they have been considered to go d the disclosure as filed, as indicated in the Supplemental Box (Rule 70.2(c)).**
in	eplacemen this repo	t sheets which have been furnished to the receiving Office in response to an invitation under Article 14 are referred to ort as "originally filed" and are not annexed to this report since they do not contain amendments (Rule 70.16
** A	ny replace	ment sheet containing such amendments must be referred to under item 1 and annexed to this report.

INTERNATIONAL	PRELIMITY EXAMI	NATION REPORT

International application No.

7. Lack of unity of invention
In response to the invitation to restrict or pay additional fees the applicant has:
restricted the claims.
paid additional fees.
paid additional fees under protest.
neither restricted nor paid additional fees.
This Authority found that the requirement of unity of invention is not complied with and chose, according to Rule 68.1, not to invite the applicant to restrict or pay additional fees.
 This Authority considers that the requirement of unity of invention in accordance with Rules 13.1, 13.2 and 13.3 is
complied with.
not complied with for the following reasons:
This examination finds that the groups of inventions described in 1-11 are linked only in the matter of being "a member for a semiconductor device having an alloy or a composite material as a base material, having a covering film comprising a hard carbon film formed on the surface of said base material to which at least one other semiconductor device is joined with resin." However, because this matter is described in prior art documents [WO, 95/31006, A1 (SILICONIX INC.), WO, 96/02942, A1 (OLIN CORP.)], this cannot constitute a special technical feature. There is no special technical feature among the inventions of claims 1-11 that are so linked as to form a single general inventive concept. Therefore, the groups of inventions set forth as claims 1-11 clearly do not satisfy the requirement for unity of invention. Furthermore, this examination finds that there are three groups of inventions described that can be classified as claims 1-2, 7-11, 3-4 and 5-6 based on the specific aspect of the inventions described in the independent claims.
 Consequently, the following parts of the international application were the subject of international preliminary examination in establishing this report:
all parts.
the parts relating to claims Nos.

V EXAMINATION REPORT

International application No.
International explication No.
P JP03/08624

V. Reasoned statement under Artic citations and explanations suppo	le 35(2) with orting such st	regard to novelty, inventive step or industrial applicability; tatement	
1. Statement		·	YES
Novelty (N)	Claims	1-11	- 153
	Claims	- A	NO
	Claims		YES
Inventive step (IS)	Claims	1-11	ио
	Clainis .		-
Industrial applicability (IA)	Claims	1-11	YES
Industrial approximation (Claims		МО
[Olulino		_

2. Citations and explanations

Claims 1, 2, and 11

Document 1: WO, 96/02942, A1 (OLIN CORPORATION), 01 February, 1996, claims 1, 12,

13, 16, 21, 22, page 7, line 16 to page 8, line 26; page 13, lines 15-24; page 15,

lines 26-30; Figs. 2, 3

Document 2: WO, 95/31006, A1 (SILICONIX INC.), 16 November, 1995, page 5, lines 19-27,

page 14, line 28 to page 19, line 14, claims 1, 7, 8

Documents 1 and 2 describe a member for a semiconductor device that is used for a heat releasing part, having an alloy or a composite material as a base material and having a covering film comprising a hard carbon film formed on the surface of said base material to which at least one other semiconductor device is joined with resin.

Document 3: JP, 10-284643, A (Sumitomo Electric Industries, Ltd.), 23 October, 1998, Par.

Nos. [0001], [0027], [0029], [0030]

Document 3 describes a member for a semiconductor device that is used for a heat sink, having an alloy comprising W and /or Mo and Cu as a primary component or a composite material as a base material, and comprising 5-40 wt% Cu.

Making the member for a semiconductor device of the alloy or the composite material that constitutes the heat releasing part as described in documents 1 and 2 a member for a semiconductor device constituting the heat releasing part described in document 3 would be obvious to a party skilled in the art.

Claims 3, 4 and 11

Document 4: JP, 2000-297301, A (Sumitomo Electric Industries, Ltd.), 24 October, 2000, Par.

Nos. [0001], [0027], [0038]; Fig. 1

Document 4 describes a member for a semiconductor device that is used for a heat releasing substrate, having an alloy comprising Al-SiC as a primary component or a composite material as a base material, and comprising 10-70 wt% SiC.

Making the member for a semiconductor device of the alloy or the composite material that constitutes a heat releasing part as described in documents 1 and 2 a member for a semiconductor device constituting a heat releasing part as described in document 4 would be obvious to a party skilled in the art.

Supplemental Box

(To be used when the space in any of the preceding boxes is not sufficient)

Continuation of Box V.2:

Claims 5, 6 and 11 Newly discovered document 5 [WO, 00/76940, & (Sumitomo Electric Industries, Ltd.), 21

December, 2000; page 1, lines 4-5; page 13, line 15 to page 18, line 19; Fig. 1] describes a member for a semiconductor device that is used for a heat releasing substrate, having an alloy comprising Si-SiC as a primary component or a composite material as a base material, and comprising 10-35 wt% Si. Making the member for a semiconductor device of the alloy or the composite material that

TO E INC.

constitutes the heat releasing part as described in documents 1 and 2 a member for a semiconductor device constituting a heat releasing part as described in newly discovered document 5 would be obvious to a party skilled in the art.

Claims 7-10

The matters described in claims 7-10 are all matters that are ordinarily considered in the technical field of members for semiconductors; thus the inventions of these claims do not appear to involve an inventive step over the inventions of documents 1-4 or newly discovered document 5.